JJMICROELECTRONICS

60V, 50A, 9mΩ N-channel Power SGT MOSFET

JMSL0608PPD

Features

- Excellent $R_{DS(ON)}$ and Low Gate Charge
- 100% UIS TESTED
- 100% ΔVds TESTED
- Halogen-free; RoHS-compliant
- Pb-free plating

Applications

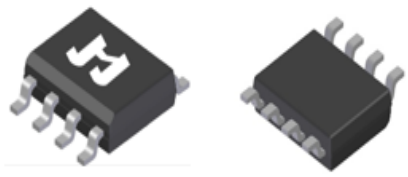
- Load Switch
- PWM Application
- Power Management

Product Summary

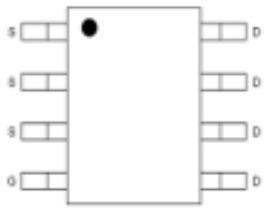
Parameters	Value	Unit
V_{DSS}	60	V
$V_{GS(th)\_Typ}$	1.7	V
I_D(@V_{GS}=10V)	50	A
$R_{DS(ON)\_Typ}$(@V_{GS}=10V	8	mΩ
$R_{DS(ON)\_Typ}$(@V_{GS}=4.5V	9	mΩ

RoHS

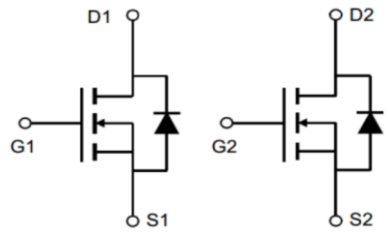
Pb Lead-free Green



SOP-8L_Dual



Pin Assignment



Schematic Diagram

Ordering Information

Device	Marking	MSL	Form	Package	Reel(pcs)	Per Carton (pcs)
JMSL0608PPD	SL0608PP	3	Tape&Reel	SOP-8L	4000	40000

Absolute Maximum Ratings (@ T_A = 25°C unless otherwise specified)

Symbol	Parameter		Value	Unit
V_{DS}	Drain-to-Source Voltage		60	V
V_{GS}	Gate-to-Source Voltage		±20	V
I_D	Continuous Drain Current	T_A = 25°C	50	A
		T_A = 100°C	35	
I_{DM}	Pulsed Drain Current (1)		Refer to Fig.4	A
E_{AS}	Single Pulsed Avalanche Energy (2)		74	mJ
P_D	Power Dissipation	T_A = 25°C	23	W
		T_A = 100°C	9	
T_J, T_{STG}	Junction & Storage Temperature Range		-55 to 150	°C

Thermal Characteristics

Symbol	Parameter	Max	Unit
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient(3)	49.5	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient(4)	5.5	

Electrical Characteristics (T_J = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	I_D = 250μA, V_{GS} = 0V	60	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} = 48V, V_{GS} = 0V	-	-	1.0	μA
I_{GSS}	Gate-Body Leakage Current	V_{DS} = 0V, V_{GS} = ±20V	-	-	±100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS} = V_{GS}, I_D = 250μA	1.2	1.7	2.3	V
$R_{DS(ON)}$	Static Drain-Source ON-Resistance(5)	V_{GS} = 10V, I_D = 12A	-	8	10	mΩ
		V_{GS} = 4.5V, I_D = 6A	-	9.4	12.2	mΩ
Dynamic Characteristics						
R_g	Gate Resistance	f = 1MHz	-	2	-	Ω
C_{iss}	Input Capacitance	V_{GS} = 0V, V_{DS} = 30V, f = 1MHz	841	1178	1590	pF
C_{oss}	Output Capacitance		367	513	693	pF
C_{rss}	Reverse Transfer Capacitance		24	34	45	pF
Q_g	Total Gate Charge	V_{GS} = 0 to 4.5V V_{DS} = 30V, I_D = 15A	15	21	29	nC
Q_{gs}	Gate Source Charge		2.8	4	5.2	nC
Q_{gd}	Gate Drain("Miller") Charge		3.4	5	6.3	nC
Switching Characteristics						
$t_{d(on)}$	Turn-On DelayTime	V_{GS} = 10V, V_{DD} = 15V I_D= 15A, R_{GEN} = 3Ω	-	7	-	ns
t_r	Turn-On Rise Time		-	24	-	ns
$t_{d(off)}$	Turn-Off DelayTime		-	22	-	ns
t_f	Turn-Off Fall Time		-	6	-	ns
Body Diode Characteristics						
I_S	Maximum Continuous Body Diode Forward Current		-	-	50	A
I_{SM}	Maximum Pulsed Body Diode Forward Current		-	-	199	A
V_{SD}	Body Diode Forward Voltage	V_{GS} = 0V, I_S = 15A	-		1.2	V
trr	Body Diode Reverse Recovery Time	I_F = 15A, di/dt = 100A/us	22.5	32	42.6	ns
Qrr	Body Diode Reverse Recovery Charge		-	23.6	-	nC

Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
2. E_{AS} condition: Starting T_J=25C, V_{DD}=30V, V_G=10V, R_G=25ohm, L=3mH, I_{AS}=7A, V_{DD}=0V during time in avalanche.
3. $R_{\theta JA}$ is measured with the device mounted on a minimum recommended pad of 2oz copper FR4 PCB.
4. $R_{\theta JA}$ is measured with the device mounted on a 1inch^2 pad of 2oz copper FR4 PCB.
5. Pulse Test: Pulse Width≤300μs, Duty Cycle≤0.5%.

Typical Performance Characteristics

Figure 1: Power De-rating

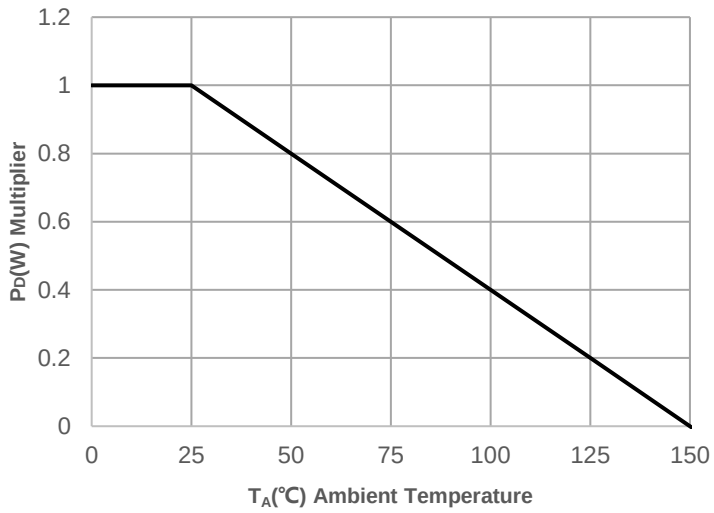


Figure 2: Current De-rating

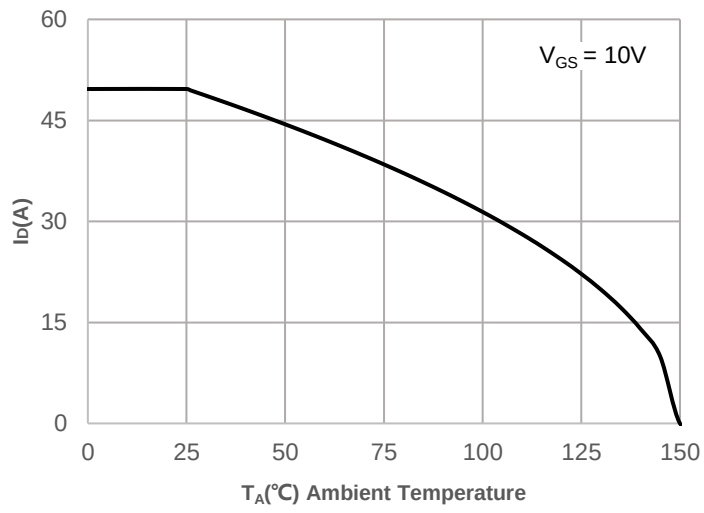


Figure 3: Normalized Maximum Transient Thermal Impedance

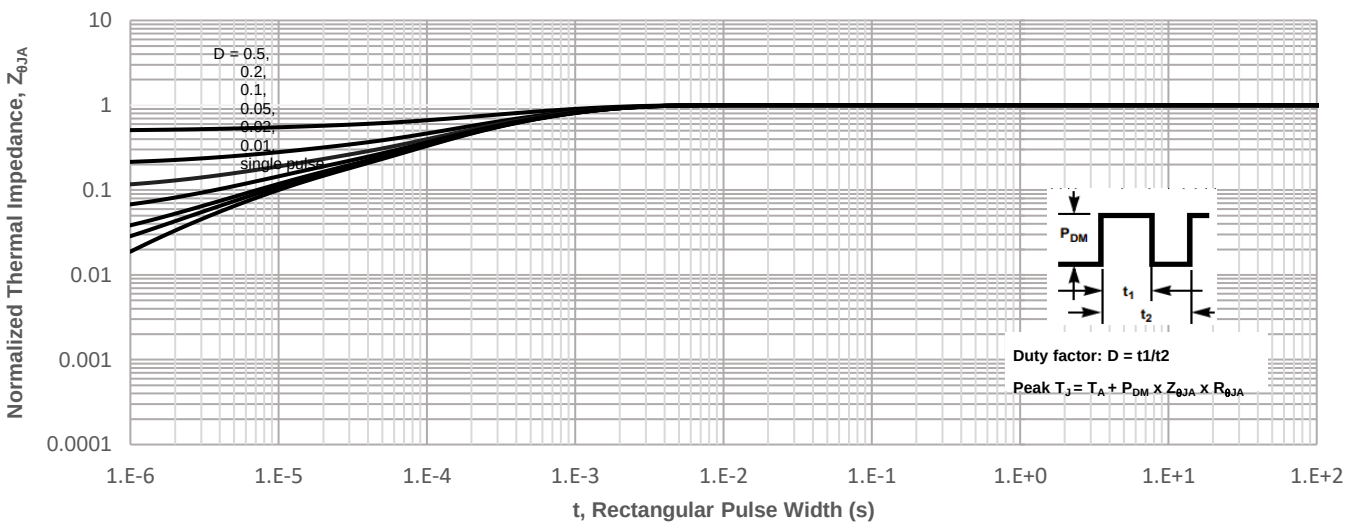
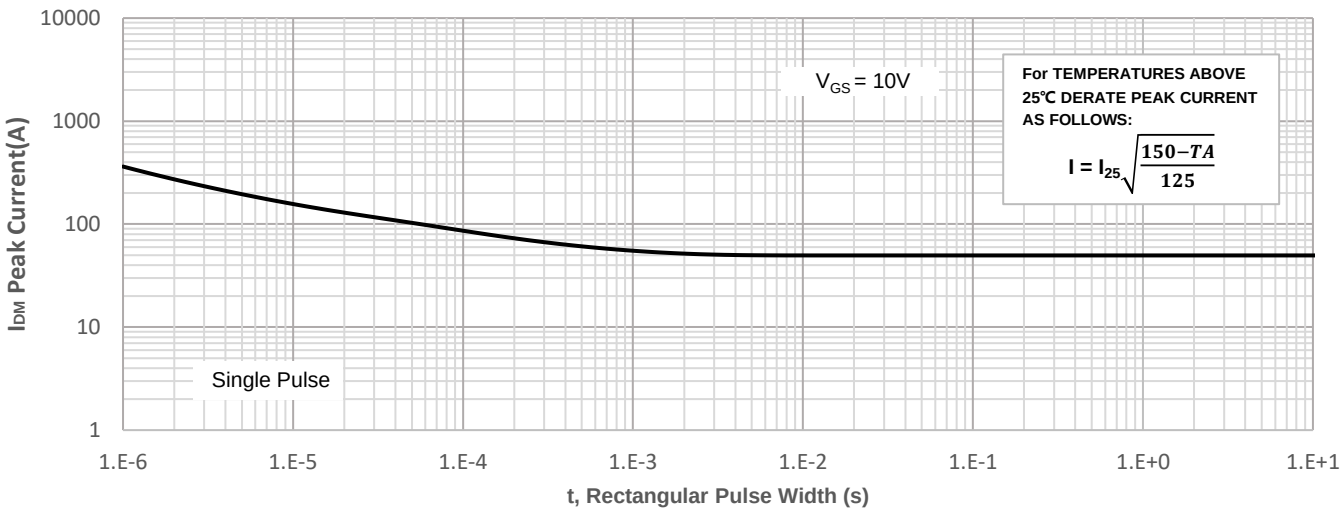


Figure 4: Peak Current Capacity



Typical Performance Characteristics

Figure 5: Output Characteristics

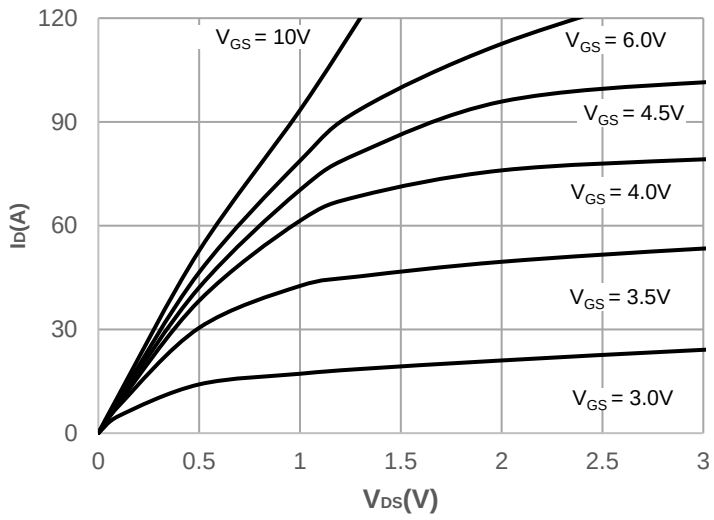


Figure 6: Typical Transfer Characteristics

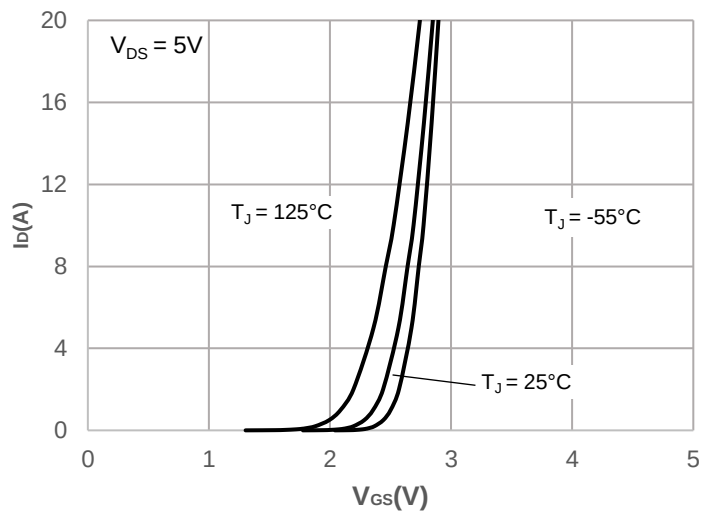


Figure 7: On-resistance vs. Drain Current

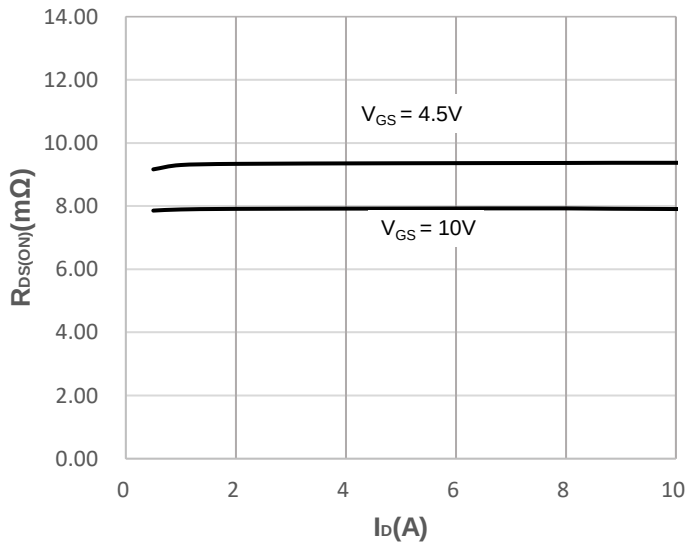


Figure 8: Body Diode Characteristics

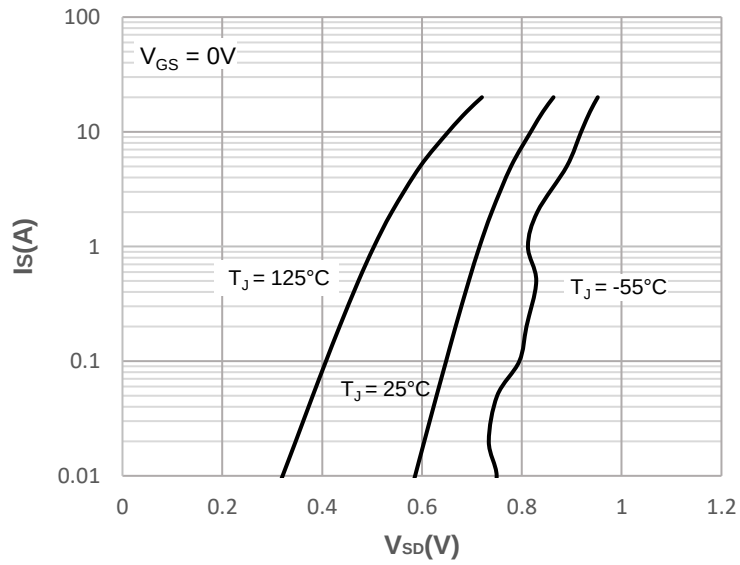


Figure 9: Gate Charge Characteristics

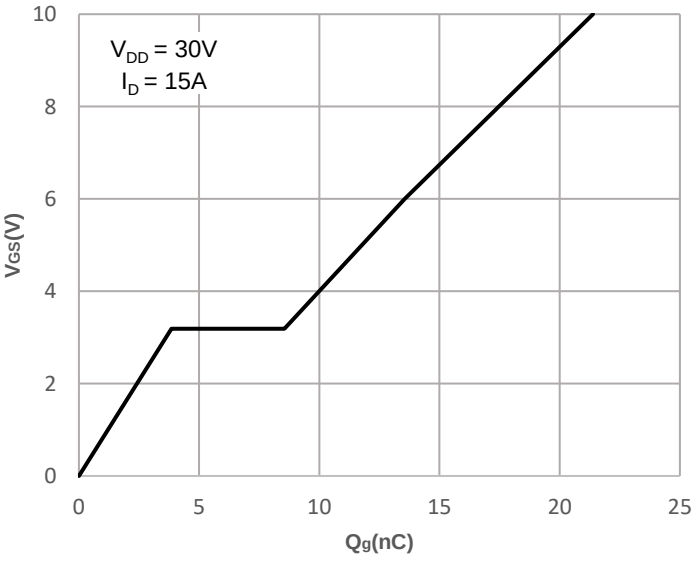
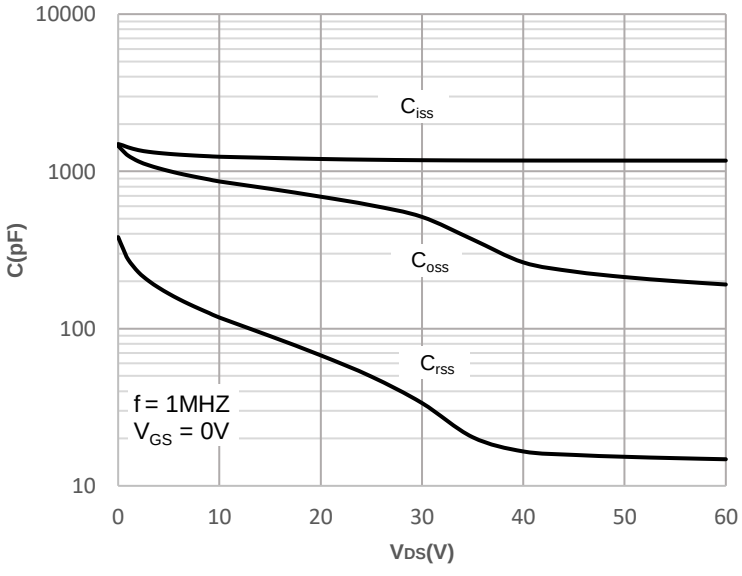


Figure 10: Capacitance Characteristics



Typical Performance Characteristics

Figure 11: Normalized Breakdown voltage vs. Junction Temperature

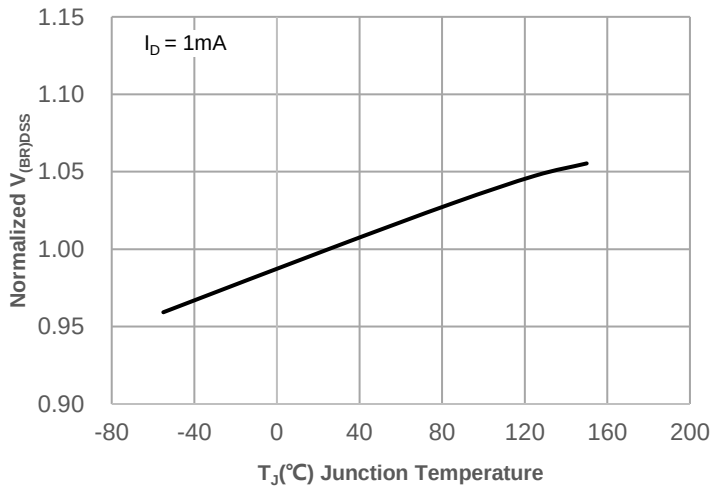


Figure 12: Normalized on Resistance vs. Junction Temperature

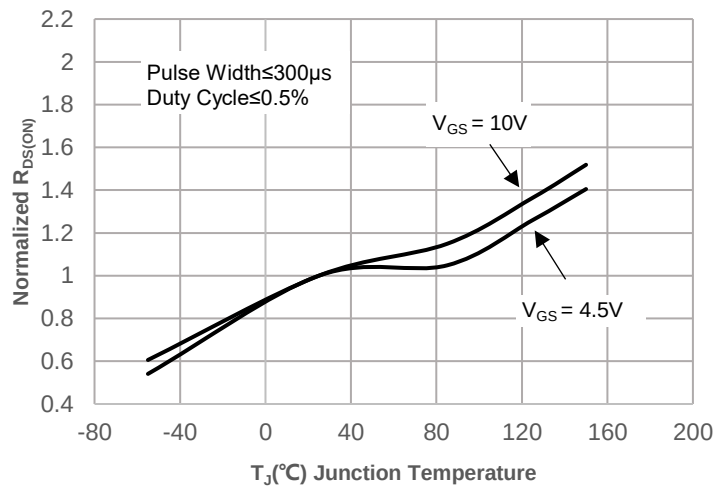


Figure 13: Normalized Threshold Voltage vs. Junction Temperature

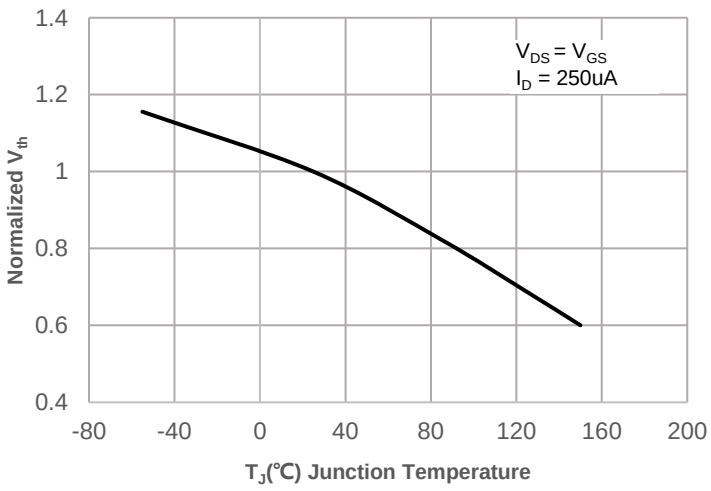


Figure 14: $R_{DS(ON)}$ vs. V_{GS}

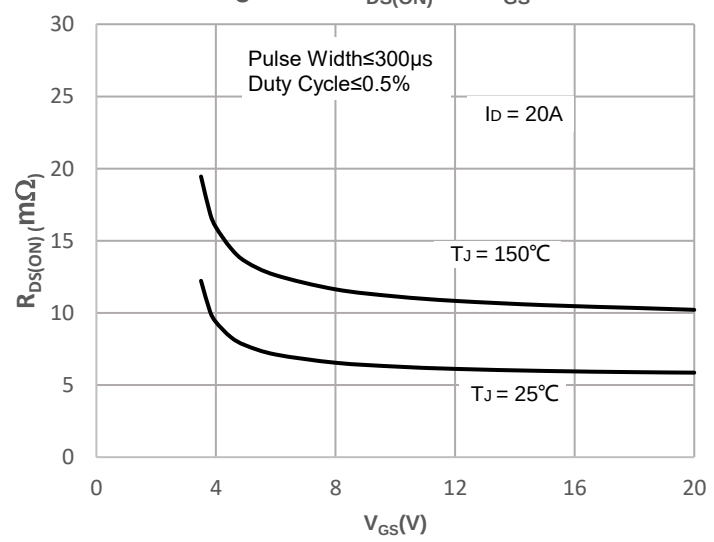
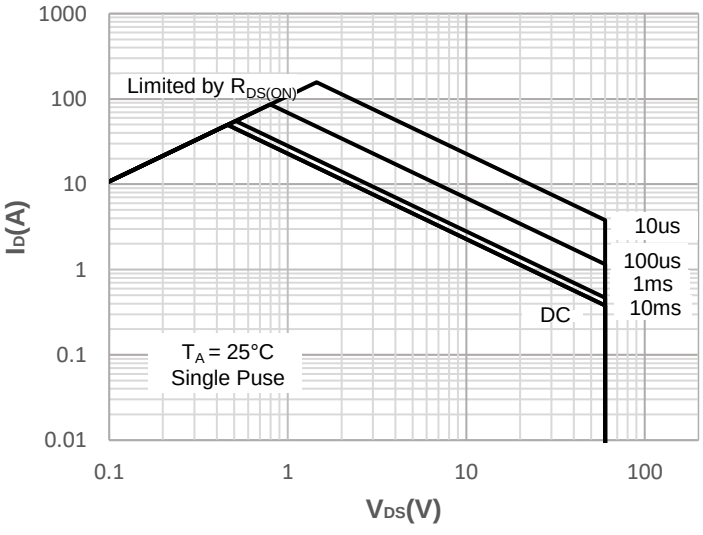


Figure 15: Maximum Safe Operating Area



Test Circuit

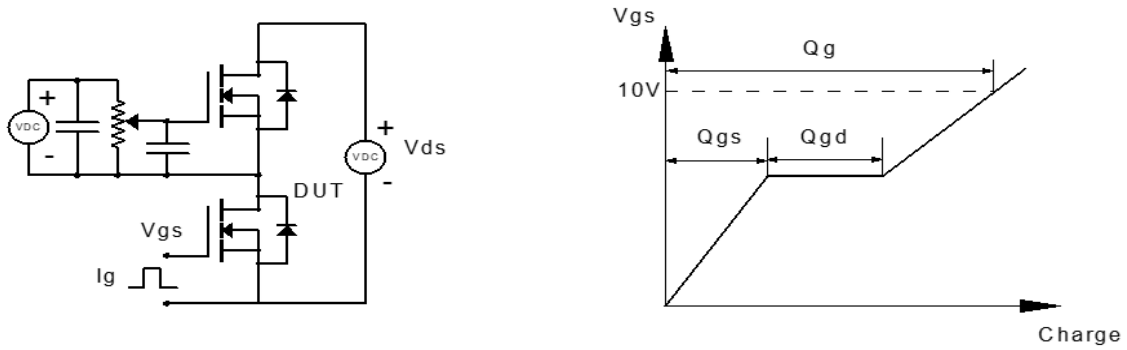


Figure 1: Gate Charge Test Circuit & Waveform

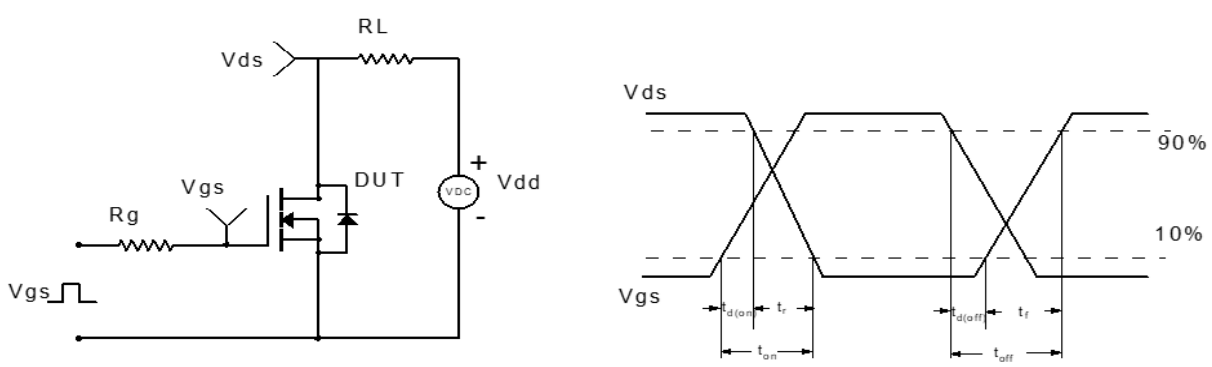


Figure 2: Resistive Switching Test Circuit & Waveform

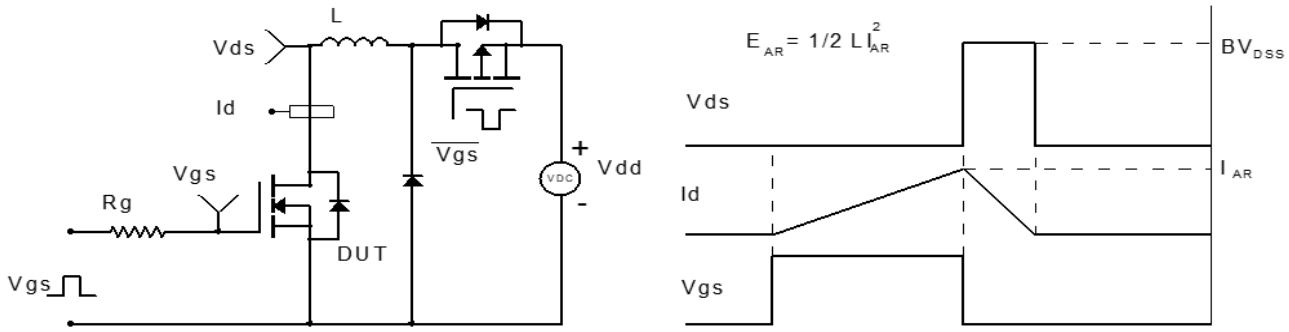


Figure 3: Unclamped Inductive Switching Test Circuit& Waveform

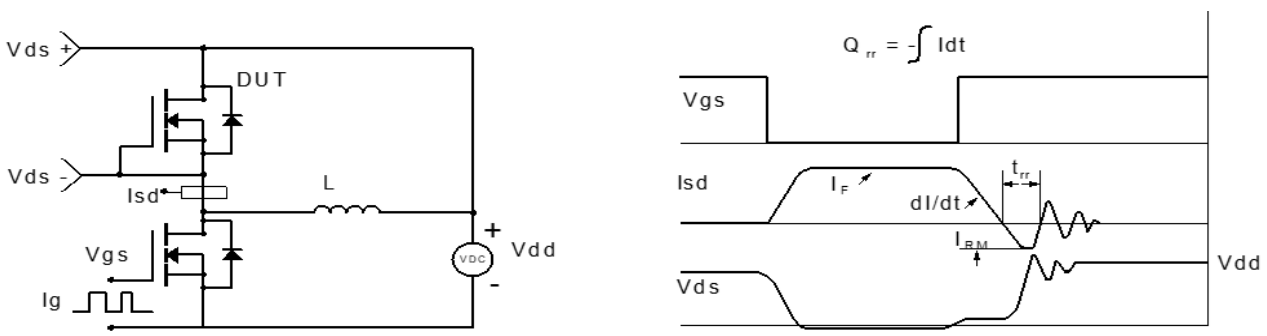
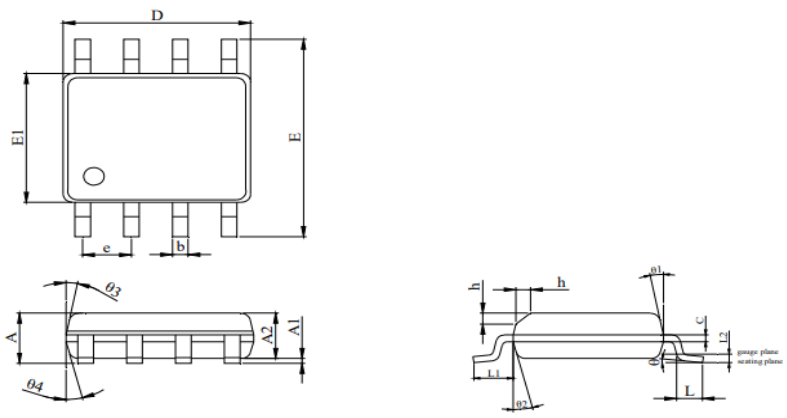


Figure 4: Diode Recovery Test Circuit & Waveform

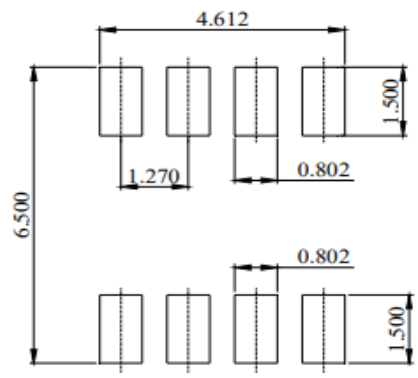
Package Mechanical Data(SOP-8L)

Package Outline



DIM	MILLIMETER		
	MIN.	NOM.	MAX.
A	1.35	1.50	1.65
A1	0.05	0.10	0.15
A2	1.35	1.40	1.50
b	0.38	--	0.50
c	0.17	--	0.25
D	4.80	4.90	5.00
E	5.80	6.00	6.20
E1	3.80	3.90	4.00
e	1.27(BSC)		
L	0.45	0.60	0.80
L1	1.04 REF		
L2	0.25 BSC		
h	0.30	0.40	0.50
θ	0°	--	8°
θ_1	10°	12°	14°
θ_2	8°	10°	12°
θ_3	10°	12°	14°
θ_4	8°	10°	12°

Recommended Footprint



DIMENSIONS:MILLIMETERS